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REA BONDABLE MAGNET WIRE

Recommended Bonding Procedure:

Bondcoat	Heat Activation Temp.	Active Solvents
Reabond A	120 – 140° C	Alcohol
Reabond B	180 - 220° C	MEK (METHYL ETHYL KETONE)
Reabond S	190 - 210° C	Not Recommended

Bondable Grades (Overall Dimensions)

Type	Minimum Dielectric Film Build	Maximum Overall Diameter With Adhesive Coating
1	Equal to Single Build	Equal to Heavy Overall Diameter
2	Equal to Heavy Build	Equal to Triple Overall Diameter
3	Equal to Triple Build	Equal to Quadruple Overall Diameter

Reabond A Nysol 130° C

Insulation Description:

Reabond A is a bondable Butyral overcoat that retains good bond strength up to 130° C. Reabond A is applied over Nysol insulated magnet wire. Reabond A Nysol is a solderable insulation that is also capable of being bonded by the application of either heat (135° C to 150° C) or denatured alcohol.

Available Conductors		Available Builds	Available AWG sizes	Rea Abbreviation	Applicable Specs.	
Configuration	Metal				NEMA	IEC
Round	Copper	Type 1 Type 2	14 - 33	RANS1R RANS2R	MW 29-C	

Typical Applications	Features and Benefits
Self-Supporting Coils	Replaces varnish to set coils.
Yoke Coils	Combines bondability with ease of solderability.
Voice Coils	Soldering Temperature must be above 390° C.
Inductors	Denatured alcohol or heat-activated bondcoat.

Reabond B Therm ID 180° C

Insulation Description:

Reabond B is a bondable thermoplastic phenoxy overcoat applied to Therm ID and retains good bond strengths up to 150° C. Reabond B is not solderable but has a thermal rating of 180° C. Reabond B Therm ID is capable of being bonded by the application of either heat or MEK.

Available Conductors		Available Builds	Available AWG sizes	Rea Abbreviation	Applicable Specs.	
Configuration	Metal				NEMA	IEC
Round	Copper	Type 1 Type 2	14 - 33	RBI1 RBI2		

Typical Applications	Features and Benefits
Self-Supporting Coils	Replaces varnish to set coils and windings
Motors Yoke Coils	Has good windability characteristics and can withstand high-speed, automated winding operations
Voice Coils	No preheating is necessary in most encapsulating processes
Inductors	Excellent cut-through resistance, dielectric strength and moisture resistance.

To be used as a guideline only We thank REA Wire for this information.

For more information please go to http://www.reawire.com

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